



Call for Papers

Submission Deadline is November 7, 2016

IEEE CICC is sponsored by the IEEE Solid-State Circuits Society and technically co-sponsored by the IEEE Electron Devices Society

CICC 2017 welcomes submissions of original and unpublished work on:

Power Management circuits and techniques for power generation, conversion, distribution, monitoring and integration aimed to reduce overall energy consumption and increase power efficiency including adaptive techniques, IP/SOC/System level power and thermal management techniques, regulators, DC-DC converters, power control and management circuits, energy-harvesting and wireless power circuits.

Analog Circuits and Techniques for areas such as communications, biomedical, aerospace, automotive, energy, environment, computing and security applications, ranging from basic building blocks to silicon sensors, interfaces, and novel clock generation architectures.

Data Converters of all types enabled by new techniques, architectures, or circuit topologies.

Wireless Transceivers and RF Circuits for low-power and energy-efficient links, biomedical and wireless sensor networks and IoT applications, cellular connectivity including M2M applications (LTE-M, NB-IoT), emerging broadband and MIMO networks (5G, WLAN), millimeter-wave and THz systems (radar, sensing and imaging).

Wireline Communications Circuits and Systems for electrical and optical communications, including serial links and components for intra-chip and chip-to-chip interconnections, high-speed memory and graphics interfaces, backplanes, long-haul, and power line communications.

Design Foundations: modeling, simulation, manufacturing, and testing, to improve design quality and design efficiency. Topics include modeling of advanced CMOS (e.g., FinFET, FD-SOI) and beyond-CMOS devices (e.g., GaN, Non-Volatile Memories) design methodologies for emerging applications (deep learning, automobile, IoT, security), and design for manufacture, test, and reliability (novel DFT circuits, system-level testing, SoC verification).

Emerging Technologies solicits hardware focused papers in the technologies of tomorrow. This includes, but is not limited to, biomedical SOCs, sensors and MEMS, hardware based machine learning, emerging memories, silicon photonics, disruptive digital design, large area electronics, implementations in non-CMOS and hybrid process technologies.

Conference Technical Sessions and Events

Technical Sessions addressing a broad range of circuits, applications, design techniques, tools, test, reliability, and emerging technologies, and providing education on new, state-of-the-art developments is the core of the CICC technical program.

Educational Sessions instructed by recognized invited speakers who are among the best in the industry are included in the conference. They are valuable opportunities to refresh key skills in traditional circuit-design methods and acquire knowledge in vital new areas in analog, digital, and RF integrated circuit design

Panels, Forums and a **Plenary Session** provide a platform for leaders from the IC industry and academia to present highlights on new field of research and development related to circuit design and to debate key issues and controversial topics. CICC panels are well known for their lively and thought-provoking discussion and audience participation.

Our **Exhibit**, is where semiconductor manufacturers, IP providers, SW tool suppliers, design-service houses, and technical book publishers offer of their products. Our **Welcome Reception**, **Conference Reception**, **Conference Luncheon** and **Exhibit** with food and beverage, provide additional opportunities for discussion and peer networking.

Paper Submission

Papers must be **4 pages** in length, be camera-ready and **submitted electronically** in PDF format using the CICC website (www.ieee-cicc.org). Appropriate company and government clearances **MUST** be obtained prior to submission. Papers must report an **original unpublished work** and concisely explain how the state-of-the-art is advanced, including results. Circuit-design papers must include measured experimental results that substantiate performance claims. Deadline for submission of technical papers is **November 7, 2016**. Authors of accepted papers will be notified by email by **January 15, 2017**. Top-rated papers are also eligible for publication in a special issue of the **IEEE Journal of Solid State Circuits** and the **IEEE Transactions on Circuits Systems**.

For more information on paper submission, please visit the conference website (www.ieee-cicc.org). On the menu at the top, click on Call for Papers, then Abstract Submissions or contact the organization committee:

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